L Number	Hits	Search Text	DB	Time stamp
-	3461	((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 16:08
-	928	(((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:02
-	669	((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:03
-	386	(((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)) and interconnect$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:04
-	141	((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)) and interconnect$3) and ((copper or cu) same interconnect$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:04
-	139	(((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)) and interconnect$3) and ((copper or cu) same interconnect$3)) and (gold or au or aluminum or al or aluminium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:05
-	74	((((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)) and interconnect$3) and ((copper or cu) same interconnect$3)) and (gold or au or aluminum or al or aluminium)) and (substrate same (silicon or si or gaas or inp))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:05
-	24	(((((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)) and interconnect$3) and ((copper or cu) same interconnect$3)) and (gold or au or aluminum or al or aluminium)) and (substrate same (silicon or si or gaas or inp))) and (ultrasonic or thermosonic or welding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:06
-	15	(((((((((438/118) or (438/119) or (438/612) or (438/615) or (438/616) or (438/617)).CCLS.) and (metal same chip)) and ((wire or wir$3) same bond$3)) and interconnect$3) and ((copper or cu) same interconnect$3)) and (gold or au or aluminum or al or aluminium)) and (substrate same (silicon or si or gaas or inp))) and (bond$3 same(ultrasonic or thermosonic or welding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 03:06

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